As partial technical support for the MicroCure Technology, Lambda offers process development and optimization assistance to include process trials.

The Lambda Technologies MicroCure 5100 is designed around the unique Variable Frequency Microwave process technique for the selective, rapid, and uniform processing of materials.

**Benefits**

VFM processing has several specific advantages over other technologies:

- **Rapid and selective heating when compared to conventional ovens**
- **Uniform energy distribution**
- **Precise Process Cycle Control**
- **Rapid sweep over controlled bandwidth allows processing of electronics packaging assemblies without arcing and circuit damage**

**System operating features include:**

- **Automated cycle control and data acquisition**
- **Pre-set process parameters, programmable for product type and quantity**
- **User-defined profiling event cycles**
- **Characterization routines for materials/process optimization**
- **IR Temp Monitoring System for closed loop feedback**
- **Auto Ramp Software - Provides accurate temp and ramp rate control**

**Accessories and Options**

- **4 Channel Fiber Optic Temp Monitoring**
- **Cavity exhaust systems**
- **Microwave compatible specialized carriers and fixtures**

**Technical Specifications**

- **Microwave Power:** 700, 1800 Watts
- **Frequency Range:** 5.8 to 7.0 GHz, 7.3 to 8.7 GHz
- **Sweep Rate Adjust:** 0.1 to 60 seconds
- **Temperature Control:** IR, Non-contact, to 385°C
- **Temperature Monitor:** Up to 4 channels, to 265°C
- **Cavity Size:** 13” H x 45” W x 18” D
- **Dimensions:** 60” H x 54” W x 41” D
- **Weight:** 1500 lbs/680kg

**Conveyor Specifications**

- **Edge Rail:** .187”(.475cm) edge clearance
  1” (2.54cm) top and bottom clearance
  SMEMA compatible
- **Substrate:** Max. size 12” X 12”
  (30.5cm X 30.5cm)
  Min size 4” X 2”
  (10.2cm X 5.1cm)
- **Board Stops:** 3 to 6 depending upon substrate/carrier size

**Applications**

- **Industrial bonding/processing**
- **Flip chip**
- **COB (Chip On Board)**
- **MCM assembly**
- **Semiconductors**
- **Fiber Optics Component Assembly**
- **Structural Bonding**
- **Smart Cards/RFID Tag**